

Silicon Carbide (SiC) MOSFET - 13.5 mohm, 750 V, M2, TO-247-4L

NVH4L018N075SC1

Features

- Typ. $R_{DS(on)} = 13.5 \text{ m}\Omega$ @ $V_{GS} = 18 \text{ V}$ Typ. $R_{DS(on)} = 18 \text{ m}\Omega$ @ $V_{GS} = 15 \text{ V}$
- Ultra Low Gate Charge (Q_{G(tot)} = 262 nC)
- High Speed Switching with Low Capacitance (Coss = 365 pF)
- 100% Avalanche Tested
- AEC-Q101 Qualified and PPAP Capable
- This Device is Halide Free and RoHS Compliant with exemption 7a, Pb–Free 2LI (on second level interconnection)

Typical Applications

- Automotive On Board Charger
- Automotive DC-DC Converter for EV/HEV
- Automotive Traction Inverter

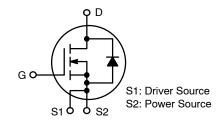
MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V _{DSS}	750	V
Gate-to-Source Voltage	Gate-to-Source Voltage			-8/+22	V
	Recommended Operation Values of Gate-to-Source Voltage		V_{GSop}	-5/+18	>
Continuous Drain Current (Note 1)	Steady State	T _C = 25°C	I _D	140	Α
Power Dissipation (Note 1)			P _D	500	W
Continuous Drain Current (Note 1)	Steady State	T _C = 100°C	I _D	99	Α
Power Dissipation (Notes 1)			P _D	250	V
Pulsed Drain Current (Note 2)	T _C = 25°C		I _{DM}	483	Α
Single Pulse Surge Drain Current Capability	T_A = 25°C, t_p = 10 μ s, R_G = 4.7 Ω		I _{DSC}	807	Α
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +175	°C
Source Current (Body Diode)			I _S	108	Α
Single Pulse Drain-to-Source Avalanche Energy (I _{L(pk)} = 18 A, L = 1 mH) (Note 3)			E _{AS}	162	mJ
Maximum Lead Temperature for Soldering (1/8" from case for 5 s)			T _L	300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Repetitive rating, limited by max junction temperature.
- 3. EAS of 162 mJ is based on starting $T_J = 25^{\circ} \mbox{C}$; L = 1 mH, $I_{AS} = 18$ A, $V_{DD} = 50$ V, $V_{GS} = 18$ V.

V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
750 V	18 mΩ @ 18 V	140 A



N-CHANNEL MOSFET



TO247-4L CASE 340CJ

MARKING DIAGRAM



H4L018N075SC = Specific Device Code

A = Assembly Location

Y = Year WW = Work Week ZZ = Lot Traceability

ORDERING INFORMATION

Device	Package	Shipping
NVH4L018N075SC1	TO247-4L	30 Units / Tube

Table 1. THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Case - Steady State (Note 4)	$R_{ heta JC}$	0.3	°C/W
Junction-to-Ambient - Steady State (Notes 4)	$R_{ heta JA}$	40	

^{4.} The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS	•						
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 1 mA		750	-	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J	I _D = 1 mA, referenced	I _D = 1 mA, referenced to 25°C		0.06	-	V/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V,	T _J = 25°C	-	-	10	μΑ
		V _{DS} = 750 V	T _J = 175°C	-	-	1	mA
Gate-to-Source Leakage Current	I _{GSS}	$V_{GS} = +18/-5 \text{ V}, V_{DS} = 0 \text{ V}$		-	-	250	nA
ON CHARACTERISTICS (Note 2)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_{D} = 22 \text{ m}$	ıΑ	1.8	2.7	4.3	V
Recommended Gate Voltage	V_{GOP}			-5	-	+18	V
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 15 V, I _D = 66 A	, T _J = 25°C	_	18		mΩ
		V _{GS} = 18 V, I _D = 66 A	, T _J = 25°C	_	13.5	18	
		V _{GS} = 18 V, I _D = 66 A, T _J = 175°C			19		
Forward Transconductance	9FS	V _{DS} = 10 V, I _D = 66 A	.	_	40	-	S
CHARGES, CAPACITANCES & GATE RE	SISTANCE						
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1 MHz, V _{DS} = 375 V		_	5010	-	pF
Output Capacitance	C _{OSS}			_	365	-	
Reverse Transfer Capacitance	C _{RSS}			_	31	-	
Total Gate Charge	Q _{G(TOT)}	$V_{GS} = -5/18 \text{ V}, V_{DS} = 600 \text{ V},$ $I_{D} = 66 \text{ A}$		_	262	-	nC
Gate-to-Source Charge	Q_{GS}			_	75	-	
Gate-to-Drain Charge	Q_{GD}			-	72	-	
Gate-Resistance	R_{G}	f = 1 MHz		-	1.6	_	Ω
SWITCHING CHARACTERISTICS, VGS =	10 V				•		
Turn-On Delay Time	t _{d(ON)}	$V_{GS} = -5/18 \text{ V}, V_{DS} =$		-	24	_	ns
Rise Time	t _r	I_D = 66 A, R_G = 2.2 Ω Inductive load	}	_	24	_	
Turn-Off Delay Time	t _{d(OFF)}			_	46	_	
Fall Time	t _f			-	9.6	-	
Turn-On Switching Loss	E _{ON}			-	144	-	μJ
Turn-Off Switching Loss	E _{OFF}			-	207	-	
Total Switching Loss	E _{tot}			-	351	_	
SOURCE-DRAIN DIODE CHARACTERIS							
Continuous Source-Drain Diode Forward Current	I _{SD}	$V_{GS} = -5 \text{ V}, T_{J} = 25^{\circ}0$	С	-	-	108	Α
Pulsed Drain-Source Diode Forward Current (Note 2)	I _{SDM}			-	-	483	
Forward Diode Voltage	V _{SD}	$V_{GS} = -5 \text{ V}, I_{SD} = 66 \text{ A}, T_{J} = 25^{\circ}\text{C}$		_	4.5	_	V

Table 2. ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified) (continued)

	(0	1 / \	,				
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit	
SOURCE-DRAIN DIODE CHARACTERISTICS							
Reverse Recovery Time	t _{RR}	$V_{GS} = -5/18 \text{ V}, I_{SD} = 66 \text{ A},$	-	28	-	ns	
Reverse Recovery Charge	Q _{RR}	$dI_S/dt = 1000 A/\mu s$	-	221	-	nC	
Reverse Recovery Energy	E _{REC}	1	-	19	-	μJ	
Peak Reverse Recovery Current	I _{RRM}		-	16	-	Α	
Charge Time	Ta		-	17	-	ns	
Discharge Time	Tb		-	11	-	ns	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

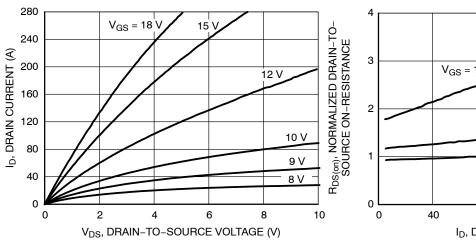


Figure 1. On-Region Characteristics

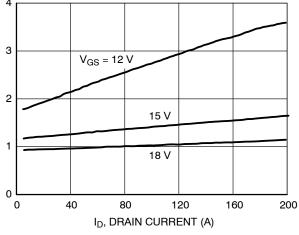


Figure 2. Normalized On-Resistance vs. Drain **Current and Gate Voltage**

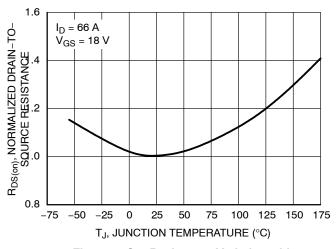


Figure 3. On-Resistance Variation with **Temperature**

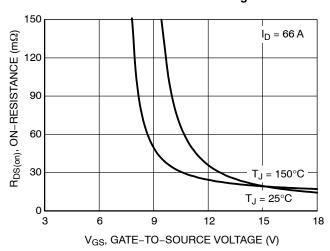


Figure 4. On-Resistance vs. Gate-to-Source Voltage

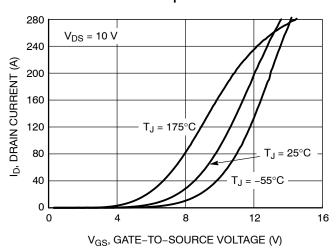


Figure 5. Transfer Characteristics

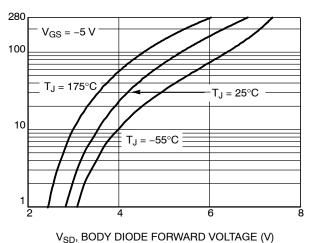


Figure 6. Diode Forward Voltage vs. Current

REVERSE DRAIN CURRENT (A)

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TYPICAL CHARACTERISTICS (continued)

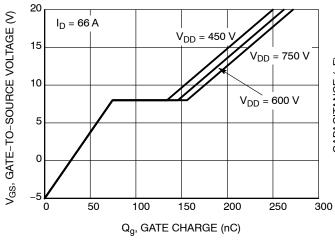


Figure 7. Gate-to-Source Voltage vs. Total Charge

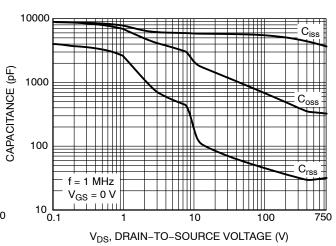


Figure 8. Capacitance vs. Drain-to-Source

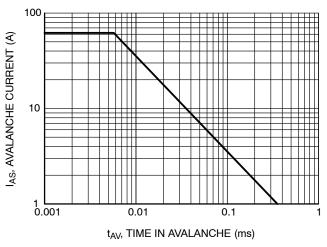


Figure 9. Unclamped Inductive Switching Capability

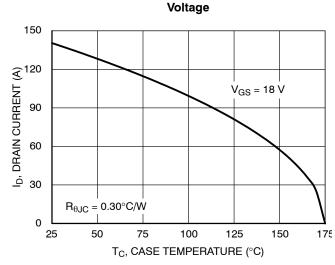


Figure 10. Maximum Continuous Drain Current vs. Case Temperature

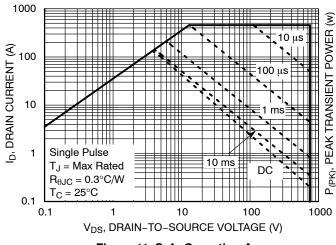


Figure 11. Safe Operating Area

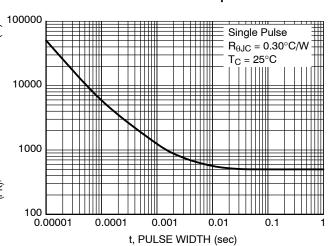


Figure 12. Single Pulse Maximum Power Dissipation

TYPICAL CHARACTERISTICS (continued)

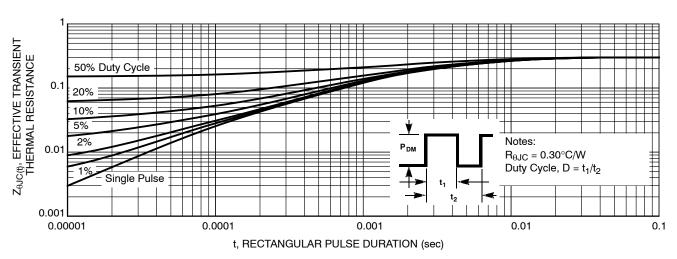
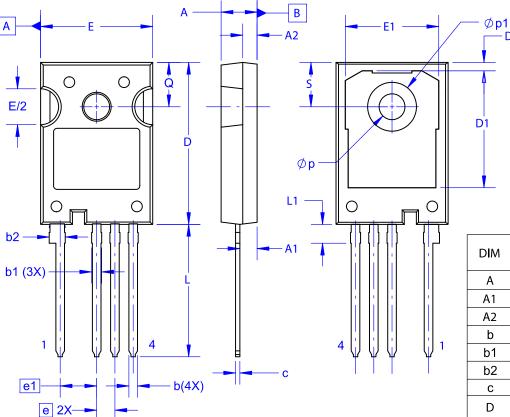


Figure 13. Junction-to-Case Thermal Response

TO-247-4LD CASE 340CJ **ISSUE A**

DATE 16 SEP 2019

D2



NOTES:

0.254 M

- A. NO INDUSTRY STANDARD APPLIES TO THIS PACKAGE.
 B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD
 FLASH, AND TIE BAR EXTRUSIONS.
 C. ALL DIMENSIONS ARE IN MILLIMETERS.
 D. DRAWING CONFORMS TO ASME Y14.5-2009.

DIM	MIN	NOM	MAX		
Α	4.80	5.00	5.20		
A1	2.10	2.40	2.70		
A2	1.80	2.00	2.20		
b	1.07	1.20	1.33		
b1	1.20	1.40	1.60		
b2	2.02	2.22	2.42		
С	0.50	0.60	0.70		
D	22.34	22.54	22.74		
D1	16.00	16.25	16.50		
D2	0.97	1.17	1.37		
е	2.54 BSC				
e1	5.08 BSC				
E	15.40	15.60	15.80		
E1	12.80	13.00	13.20		
E/2	4.80	5.00	5.20		
L	18.22	18.42	18.62		
L1	2.42	2.62	2.82		
р	3.40	3.60	3.80		
p1	6.60	6.80	7.00		
Q	5.97	6.17	6.37		
S	5.97	6.17	6.37		

MILLIMETERS

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